

ABSTRACT

An apparatus for placing a semiconductor chip as a flipchip on a substrate has a flip device for flipping the semiconductor chip. The flip device is formed as a parallelogram construction which consists of a support bracket, a first and a second swivel arm and a connecting arm. A chip gripper is arranged on the connecting arm. A drive system serves the back and forth movement of the parallelogram construction between a first limit position where the chip gripper accepts the semiconductor chip and a second limit position where the chip gripper places the semiconductor chip on the substrate.

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